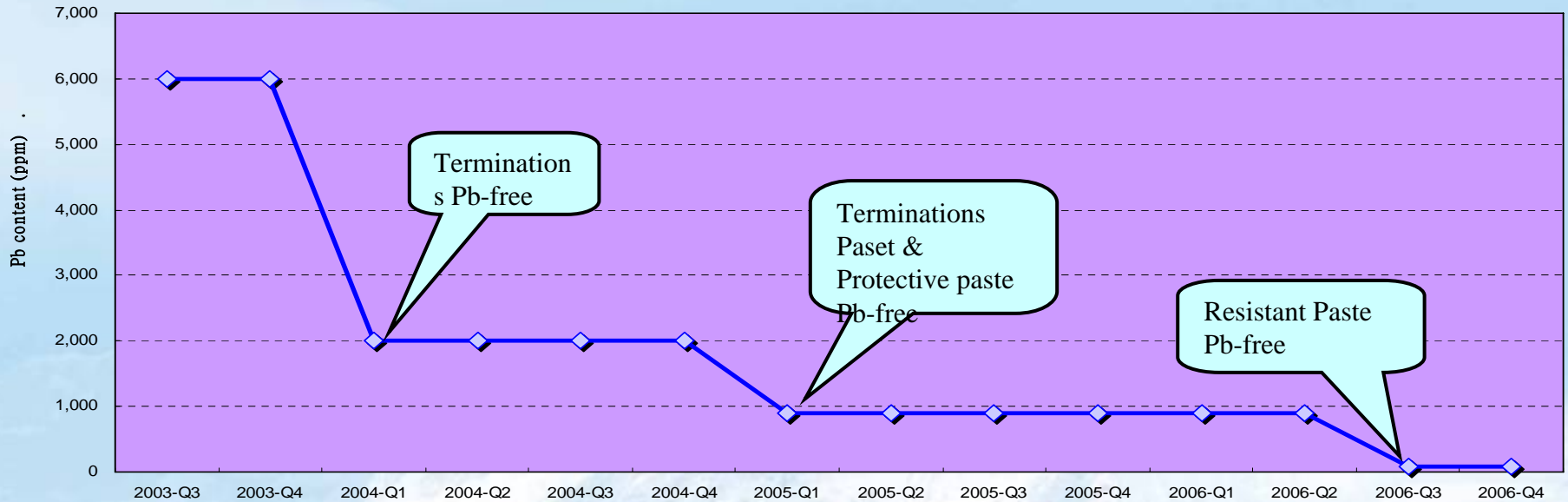


# R-Chip Pb-free improvement Plan in 2003~06



Pb Free Material	2003-Q3	2003-Q4	2004-Q1	2004-Q2	2004-Q3	2004-Q4	2005-Q1	2005-Q2	2005-Q3	2005-Q4	2006-Q1	2006-Q2	2006-Q3	2006-Q4
Termination Plating			Pure Tin ready											
Termination Paste				Pb free paste test run	Pb free product qualification & pilot run	Mass production & delivery after Sep. 2004								
Protective Paste					Pb free paste test run	Pb free product qualification & pilot run	Mass production & delivery after Feb. 2005							
Resistant Paste ~ 1K Ohmic									Pb free R-paste test run (~1K)	Pb free product qualification & pilot run	Pb free product mass production			
Resistant Paste >1K Ohmic											Pb free R paste test run (> 1K)	Pb free product qualification & pilot run	Pb free product mass production	
Date	2003-Q3	2003-Q4	2004-Q1	2004-Q2	2004-Q3	2004-Q4	2005-Q1	2005-Q2	2005-Q3	2005-Q4	2006-Q1	2006-Q2	2006-Q3	2006-Q4
Pb content (PPM)	6,000	6,000	2,000	2,000	2,000	2,000	900	900	900	900	900	900	90	90